



A cross-sectional diagram of a semiconductor device assembly. It shows a substrate 4 supporting a base layer 6. On top of the base layer are three main components: a first semiconductor element 1, a central insulating or spacer layer 8, and a second semiconductor element 7. The first element 1 has a top surface 15 and side surfaces 9. The second element 7 has a top surface 35b and side surfaces 9. Between the elements and around them are various conductive layers and contacts labeled 8, 35a, 3, 25, and 2. A wire bond 8 connects the first element to the second element.

FIG. 3 (a)

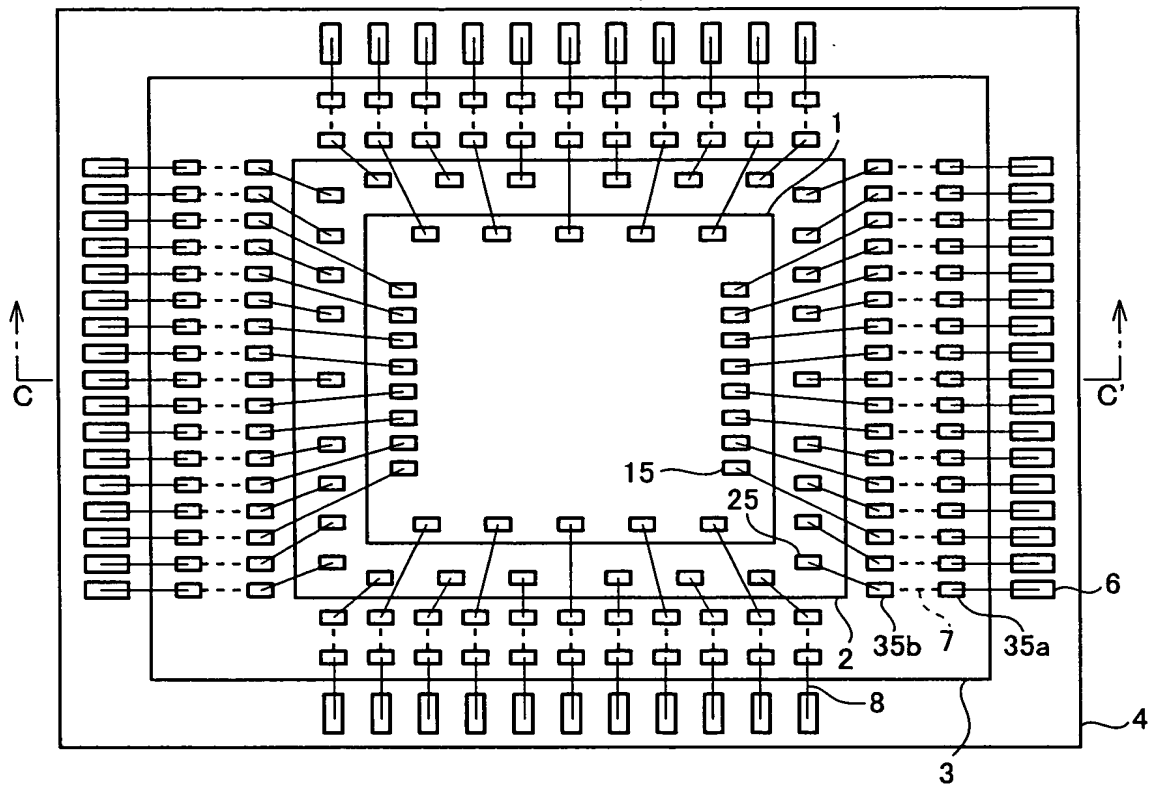


FIG. 3 (b)

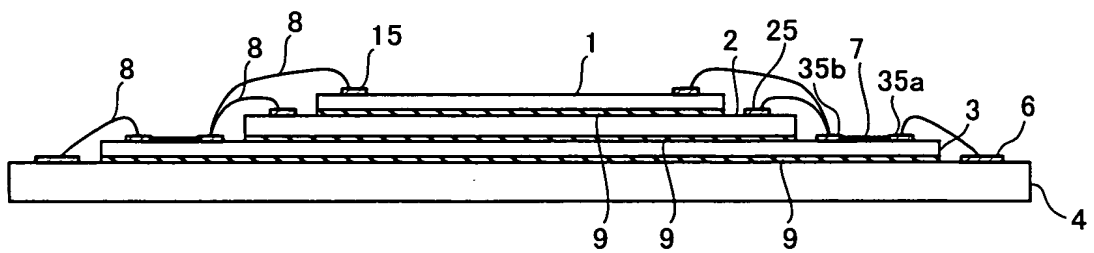


FIG. 4

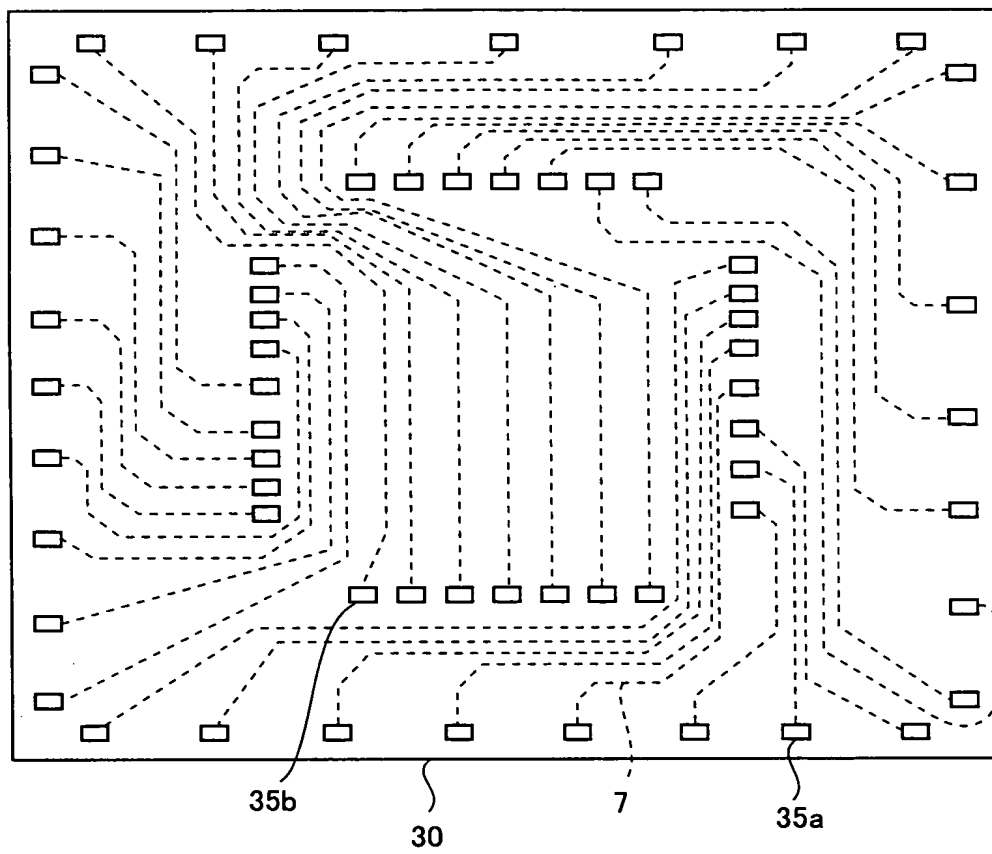


FIG. 5 (a)

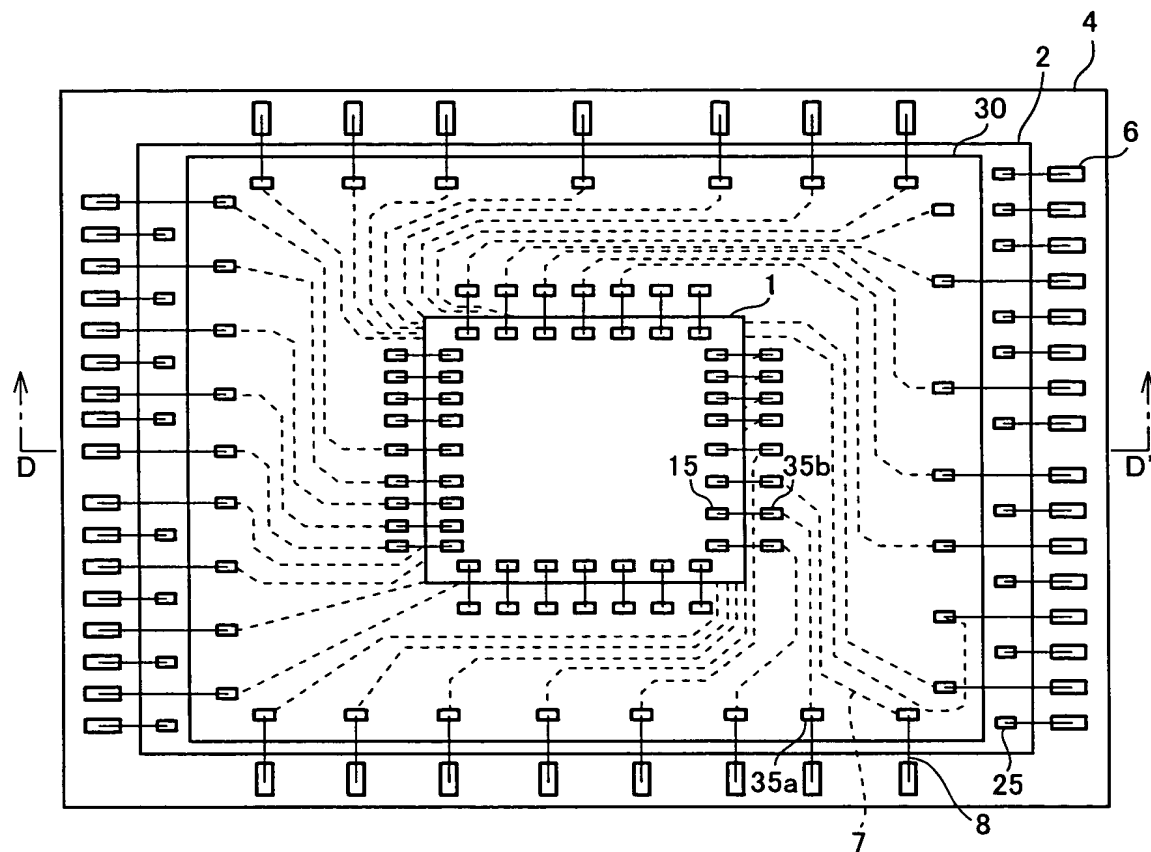


FIG. 5 (b)

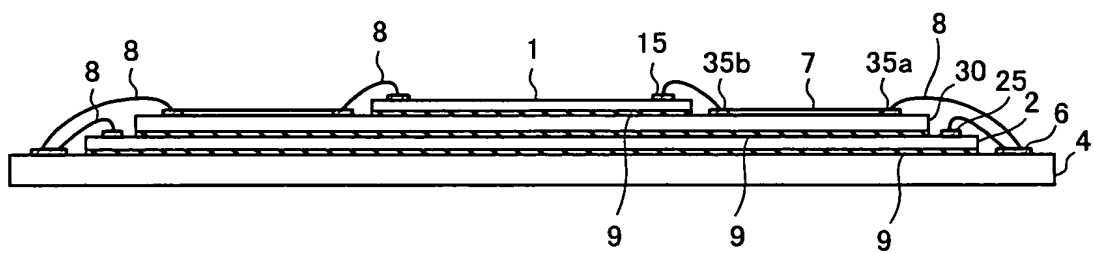


FIG. 6

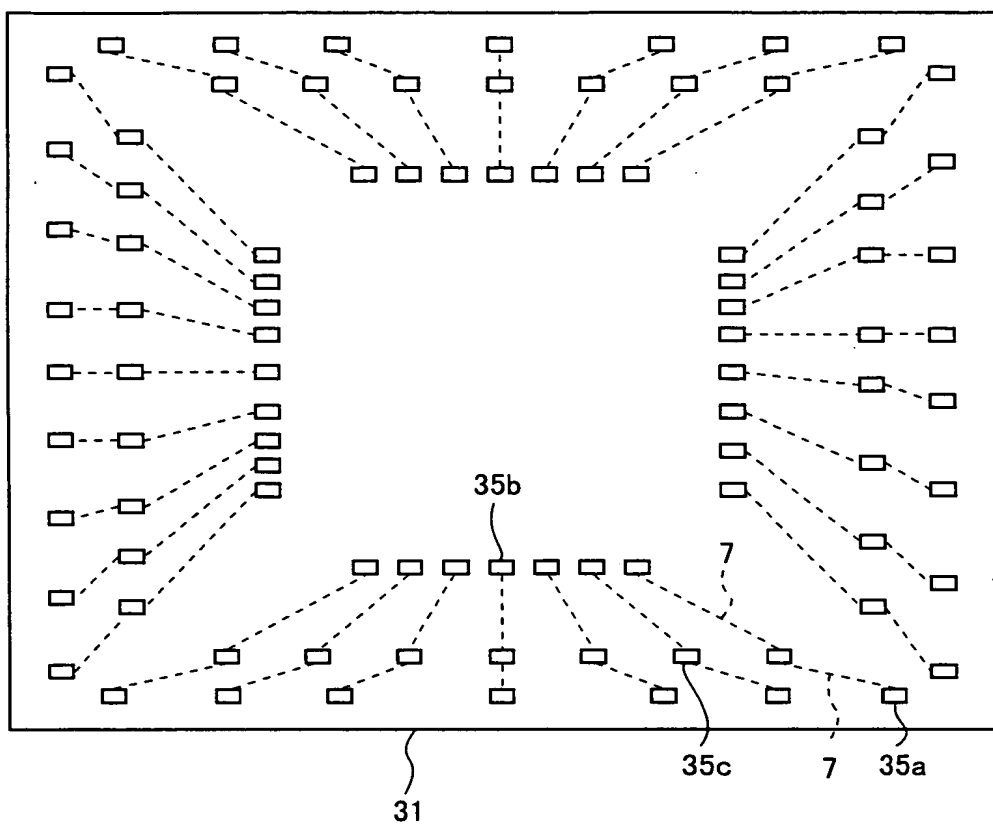


FIG. 7

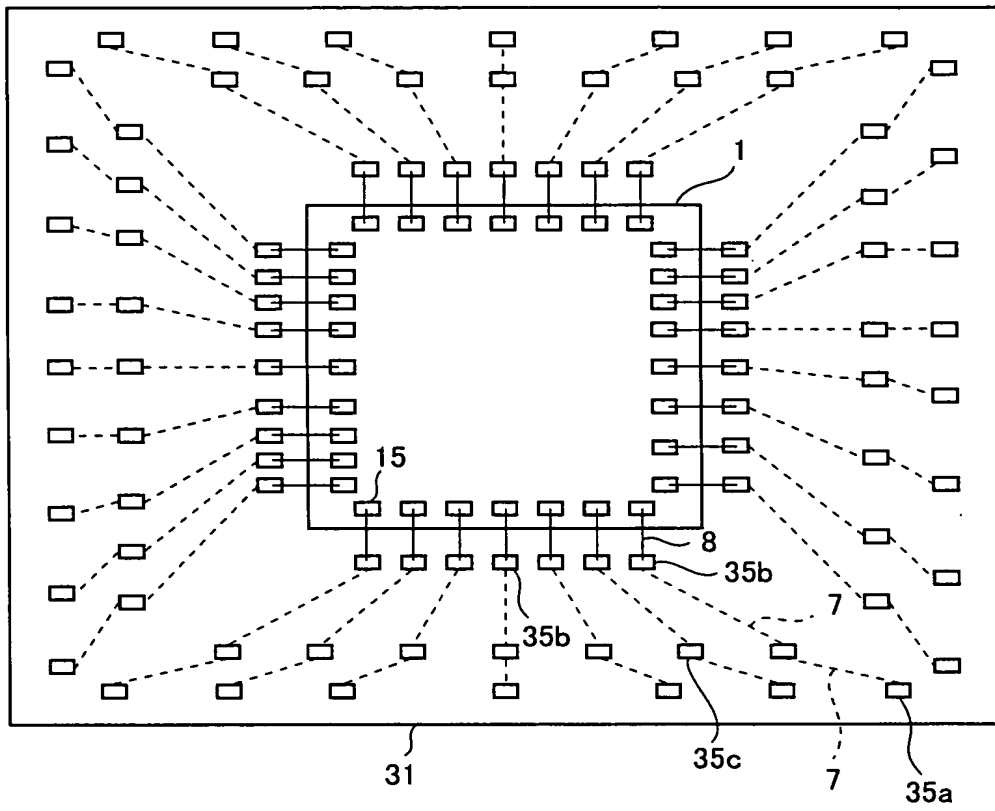


FIG. 8

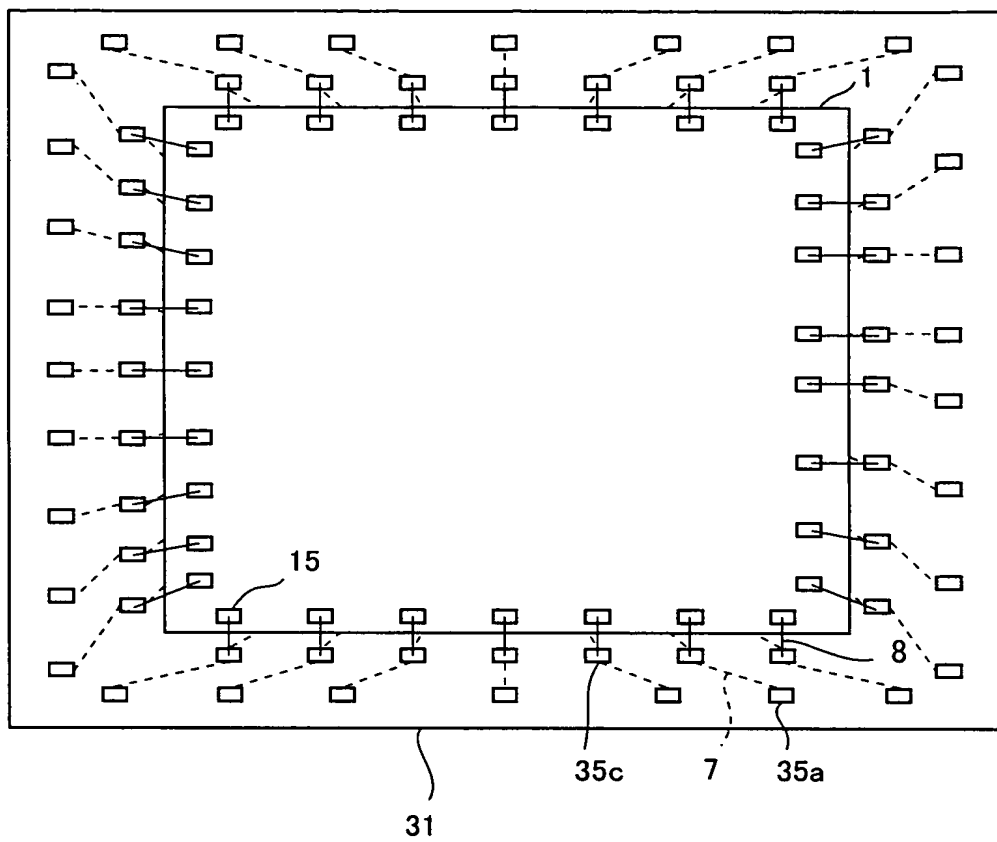




FIG. 9 (a)

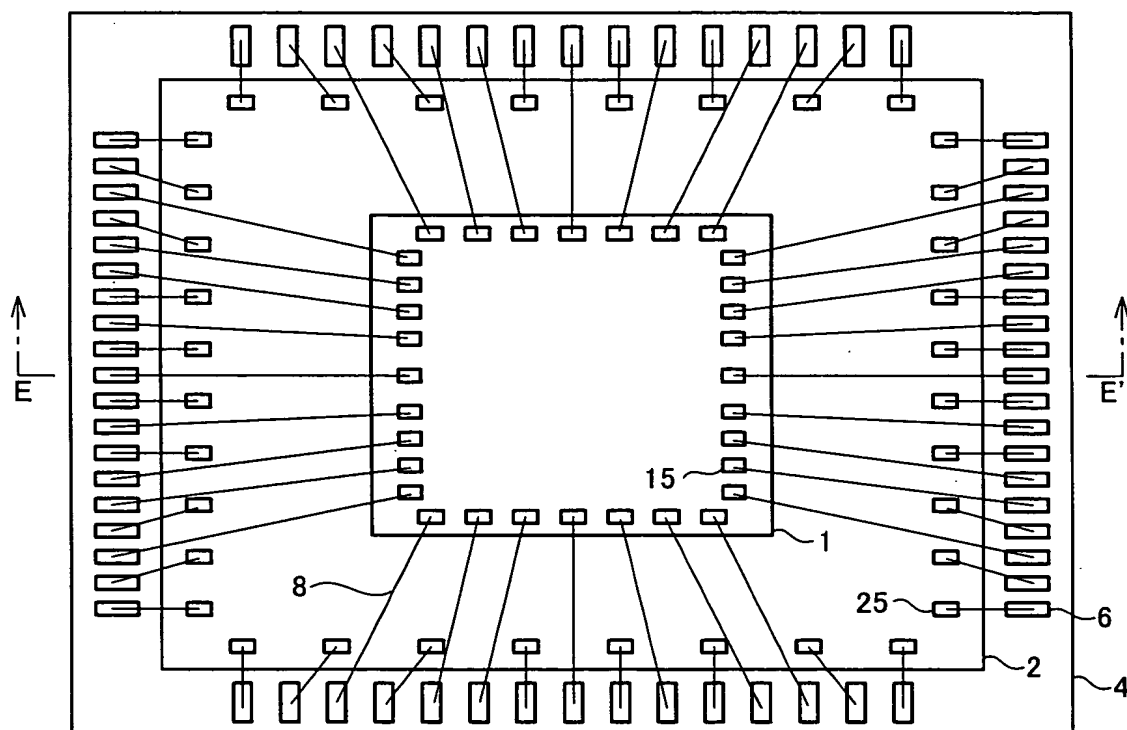


FIG. 9 (b)

